

Features :

- n Trench&field stop technology
- n 10us short circuit capability
- n Low switching losses
- n $V_{CE(sat)}$ with Positive temperature coefficient
- n Fast & soft reverse recovery anti-parallel FWD

Typical Applications :

- n Inverter for motor drive(VFD)
- n AC and DC servo drive amplifier
- n Uninterruptible power supply

IGBT, Inverter

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT
			Min	Type	Max	
V_{CES}	Collector-Emitter voltage	$T_j=25^{\circ}C$			1200	V
V_{GES}	Gate-Emitter voltage	$T_j=25^{\circ}C$			± 20	V
I_c	Collector current	Continuous@ $T_c=100^{\circ}C$			35	A
I_{CRM}		$t_p=1ms$			70	A
P_{tot}	Total power dissipation	$T_C= 25^{\circ}C, T_{vjmax}=175^{\circ}C$			215	W
$V_{GE(th)}$	Gate-Emitter threshold voltage	$T_j=25^{\circ}C, V_{CE}=20V, I_c=1.20mA$	5.2	5.8	6.4	V
$V_{CE(sat)}$	Collector-Emitter saturation voltage	$T_j=25^{\circ}C, V_{GE}=15V, I_c=35A$		1.85	2.25	V
		$T_j=25^{\circ}C, V_{GE}=15V, I_c=35A$		2.15		V
		$T_j=25^{\circ}C, V_{GE}=15V, I_c=35A$		2.25		V
Q_g	Gate Charge	$V_{GE}=\pm 15V$		0.27		μC
R_{Gint}	Integrated gate resistor	$T_j=25^{\circ}C$		2		Ω
C_{ies}	Input capacitance	$T_j=25^{\circ}C, V_{CE}=25V, V_{GE}=0V, f=1MHz$		2.00		nF
C_{oes}	output capacitance			1.80		nF
C_{res}	Reverse transfer capacitance			0.07		nF
I_{CES}	Zero gate voltage collector current	$T_j=25^{\circ}C, V_{CE}=1200V, V_{GE}=0V$			1.0	mA
I_{GES}	Gate-Emitter leakage current	$T_j=25^{\circ}C, V_{CE}=0V, V_{GE}=\pm 20V$	-0.4		0.4	μA
$t_{(d)on}$	Turn-on time	$V_{CC}=600V, I_c=35A, V_{GE}=\pm 15V, R_{gon}=12\Omega, \text{ Inductive load}$	$T_j=25^{\circ}C$	25		ns
			$T_j=125^{\circ}C$	25		ns
$T_j=150^{\circ}C$			25		ns	
t_r			$T_j=25^{\circ}C$	13		ns
			$T_j=125^{\circ}C$	16		ns
			$T_j=150^{\circ}C$	18		ns
$t_{(d)off}$	Turn-off time	$V_{CC}=600V, I_c=35A, V_{GE}=\pm 15V, R_{goff}=12\Omega, \text{ Inductive load}$	$T_j=25^{\circ}C$	240		ns
			$T_j=125^{\circ}C$	295		ns
$T_j=150^{\circ}C$			310		ns	
t_f			$T_j=25^{\circ}C$	115		ns
			$T_j=125^{\circ}C$	170		ns
			$T_j=150^{\circ}C$	200		ns
E_{on}		$I_c=35A, V_{CE}=600V, L_s=35nH, V_{GE}=\pm 15V, di/dt=2500A/\mu s (T_{vj} = 150^{\circ}C), R_{Gon}=12\Omega$	$T_j=25^{\circ}C$	1.90		mJ
			$T_j=125^{\circ}C$	2.90		mJ
			$T_j=150^{\circ}C$	3.15		mJ
E_{off}			$T_j=25^{\circ}C$	2.00		mJ
			$T_j=125^{\circ}C$	2.90		mJ
			$T_j=150^{\circ}C$	3.20		mJ

I _{sc}	Short circuit withstand current	V _{GE} =15V, V _{CC} =900V, V _{CEmax} =V _{CES} -L _{sCE} ·di/dt, t _p ≤10μs, T _{vj} =150°C		130		A
R _{th(j-c)}	Thermal resistance, junction to case	per IGBT		0.60	0.70	°C/W
R _{th(c-h)}	Thermal resistance, case to heatsink			0.60		°C/W
T _{Vjop}	Junction temperature	/	-40		150	°C
T _{stg}	Storage temperature		-40		125	°C
F	mounting force per clamp		40		80	N
W _t	Weight			39		g

Diode, Inverter

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT
			Min	Type	Max	
V _{RRM}	Repetitive peak reverse voltage	T _{vj} =25°C			1200	V
I _F	Continuous DC forward current				35	A
I _{FRM}	Repetitive peak forward current				70	A
I ² t	I ² t - value	V _R =0V, t _p =10ms, T _{vj} =150°C			220	A ² s
V _F	Forward on voltage	I _F =35A	T _j =25°C	1.65	2.15	V
			T _j =125°C	1.65		V
			T _j =150°C	1.65		V
I _{RRM}	Max. reverse recovery current	I _F =35A, - di _F /dt=2500A/μs, V _R =600V	T _j =25°C	81		A
			T _j =125°C	85		A
			T _j =150°C	88		A
Q _r	Recovered charge	I _F =35A, - di _F /dt=2500A/μs, V _R =600V	T _j =25°C	3.95		μC
			T _j =125°C	6.80		μC
			T _j =150°C	7.50		μC
E _{rec}	Reverse recovery energy	I _F =35A, - di _F /dt=2500A/μs, V _R =600V	T _j =25°C	1.50		mJ
			T _j =125°C	2.70		mJ
			T _j =150°C	2.95		mJ
R _{th(j-c)}	Thermal resistance, junction to case	per diode		0.80	0.90	°C/W
R _{th(c-h)}	Thermal resistance, case to heatsink			0.75		°C/W
T _{Vjop}	Junction temperature	/	-40		150	°C

Diode, Rectifier

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT
			Min	Type	Max	
V _{RRM}	Repetitive peak reverse voltage	T _{vj} =25°C			1600	V
I _{FRMSM}	Maximum RMS forward current per chip	T _C =100°C			60	A
I _{RMSM}	Maximum RMS current at rectifier output	T _C =100°C			60	A
I _{FSM}	Surge forward current	t _p =10ms, T _{vj} =150°C			370	A
I ² t	I ² t - value	V _R =0V, t _p =10ms, T _{vj} =150°C			685	A ² s
V _F	Forward on voltage	I _F =35A, T _j =150°C		0.95		V
I _R	reverse current	V _R =1600V, T _j =150°C		1.0		mA
R _{th(j-c)}	Thermal resistance, junction to case	per diode		1.05	1.15	°C/W
R _{th(c-h)}	Thermal resistance, case to heatsink			0.95		°C/W
T _{Vjop}	Junction temperature	/	-40		150	°C

IGBT, Brake-Chopper

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT
			Min	Type	Max	
V _{CES}	Collector-Emitter voltage	T _j =25°C			1200	V
V _{GES}	Gate-Emitter voltage	T _j =25°C			±20	V
I _C	Collector current	Continuous@ T _c =100°C			54	A
I _{CRM}		t _p =1ms			70	A
P _{tot}	Total power dissipation	T _C = 25°C, T _{vjmax} =175°C			175	W
V _{GE(th)}	Gate-Emitter threshold voltage	T _j =25°C, V _{CE} =20V, I _C =1.20mA	5.2	5.8	6.4	V
V _{CE(sat)}	Collector-Emitter saturation voltage	T _j =25°C, V _{GE} =15V, I _C =35A		1.85	2.25	V
		T _j =25°C, V _{GE} =15V, I _C =35A		2.15		V
		T _j =25°C, V _{GE} =15V, I _C =35A		2.25		V
Q _g	Gate Charge	V _{GE} =±15V		0.27		μC
R _{Gint}	Integrated gate resistor	T _j =25°C		0		Ω
C _{ies}	Input capacitance	T _j =25°C, V _{CE} =25V, V _{GE} =0V, f=1MHz		2.00		nF
C _{res}	Reverse transfer capacitance			0.07		nF
I _{CES}	Zero gate voltage collector current	T _j =25°C, V _{CE} =1200V, V _{GE} =0V			1.0	mA
I _{GES}	Gate-Emitter leakage current	T _j =25°C, V _{CE} =0V, V _{GE} =±20V	-0.4		0.4	μA
t _{(d)on}	Turn-on time	V _{CC} =600V, I _C =35A, V _{GE} =±15V, R _{Gon} =47Ω, Inductive load	T _j =25°C		70	ns
			T _j =125°C		70	ns
T _j =150°C				70	ns	
T _j =25°C				45	ns	
T _j =125°C				50	ns	
T _j =150°C				57	ns	
t _{(d)off}	Turn-off time	V _{CC} =600V, I _C =35A, V _{GE} =±15V, R _{Goff} =47Ω, Inductive load	T _j =25°C		280	ns
			T _j =125°C		440	ns
T _j =150°C				450	ns	
T _j =25°C				115	ns	
T _j =125°C				175	ns	
T _j =150°C				205	ns	
E _{on}		I _C =35 A, V _{CE} =600V, L _S =35nH, V _{GE} =±15 V, R _{Gon} =47 Ω	T _j =25°C		5.00	mJ
			T _j =125°C		6.50	mJ
			T _j =150°C		7.00	mJ
E _{off}		I _C =35 A, V _{CE} =600V, L _S =35nH, V _{GE} =±15 V, R _{Goff} =47 Ω	T _j =25°C		2.10	mJ
			T _j =125°C		3.05	mJ
			T _j =150°C		3.35	mJ
I _{sc}	Short circuit withstand current	V _{GE} =15V, V _{CC} =900V, V _{CEmax} =V _{CES} -L _S CE·di/dt, t _p ≤10μs, T _{vj} =150°C			130	A
R _{th(j-c)}	Thermal resistance, junction to case	per IGBT		0.60	0.70	°C/W
R _{th(c-h)}	Thermal resistance, case to heatsink			0.60		°C/W
T _{Vjop}	Junction temperature	/	-40		150	°C

Diode, Brake-Chopper

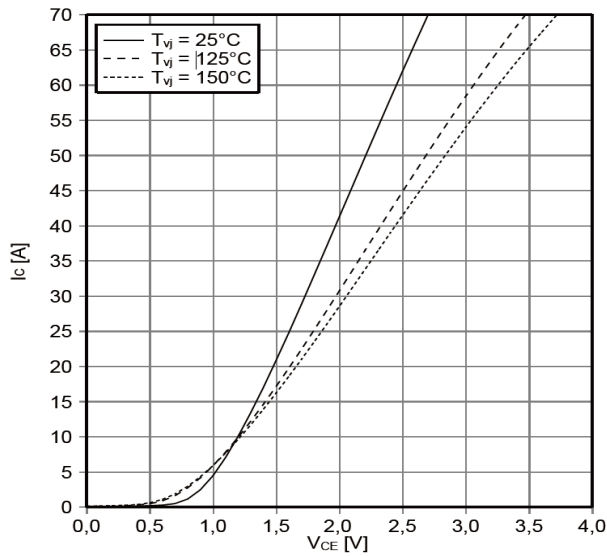
SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT
			Min	Type	Max	
V _{RRM}	Repetitive peak reverse voltage	T _{vj} =25°C			1200	V
I _F	Continuous DC forward current				10	A
I _{FRM}	Repetitive peak forward current				20	A
I ² t	I ² t - value	V _R =0V, t _p =10ms, T _{vj} =150°C			14	A ² s
V _F	Forward on voltage	I _F =10A, V _{GE} =0V	T _j =25°C	1.75	2.25	V
			T _j =125°C	1.75		V
			T _j =150°C	1.75		V
I _{RRM}	Max. reverse recovery current	I _F =10A, -di _F /dt=500A/μs, (T _{vj} =150°C), V _R =600 V	T _j =25°C	12		A
			T _j =125°C	10		A
			T _j =150°C	8		A
Q _r	Recovered charge	I _F =10A, - di _F /dt=500A/μs, V _R =600V	T _j =25°C	0.90		μC
			T _j =125°C	1.70		μC
			T _j =150°C	1.90		μC
E _{rec}	Reverse recovery energy	I _F =10A, - di _F /dt=500A/μs, V _R =600V	T _j =25°C	0.24		mJ
			T _j =125°C	0.52		mJ
			T _j =150°C	0.59		mJ
R _{th(j-c)}	Thermal resistance, junction to case	per diode		1.75	1.90	°C/W
R _{th(c-h)}	Thermal resistance, case to heatsink			1.30		°C/W
T _{vjop}	Junction temperature	/	-40		150	°C

NTC-Thermistor

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT
			Min	Type	Max	
R ₂₅	Rated resistance	T _c =25°C		5.00		k Ω
ΔR/R	Deviation of R100	T _c =100°C, R ₁₀₀ =493W	-5		5	%
P ₂₅	Power dissipation	T _c =25°C			20.0	mW
B _{25/50}	B-value	R ₂ =R ₂₅ exp [B _{25/50} (1/T ₂ -1/(298,15K))]		3375		K
B _{25/80}		R ₂ =R ₂₅ exp [B _{25/80} (1/T ₂ -1/(298,15K))]		3411		K
B _{25/100}		R ₂ =R ₂₅ exp [B _{25/100} (1/T ₂ -1/(298,15K))]		3433		K

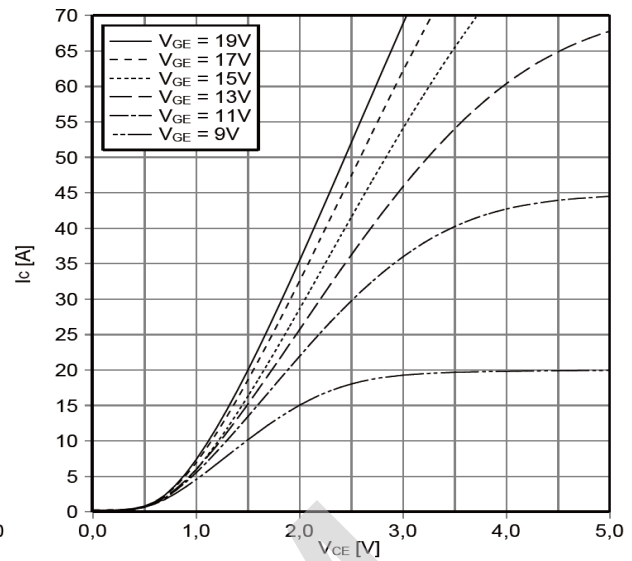
output characteristic IGBT, Inverter (typical)

$I_c = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



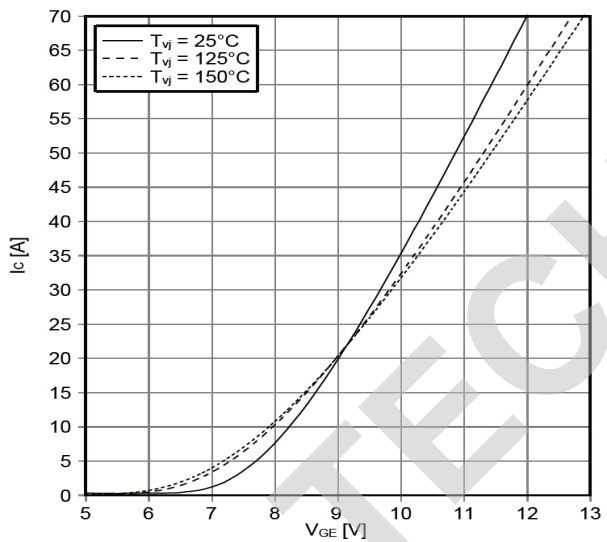
output characteristic IGBT, Inverter (typical)

$I_c = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



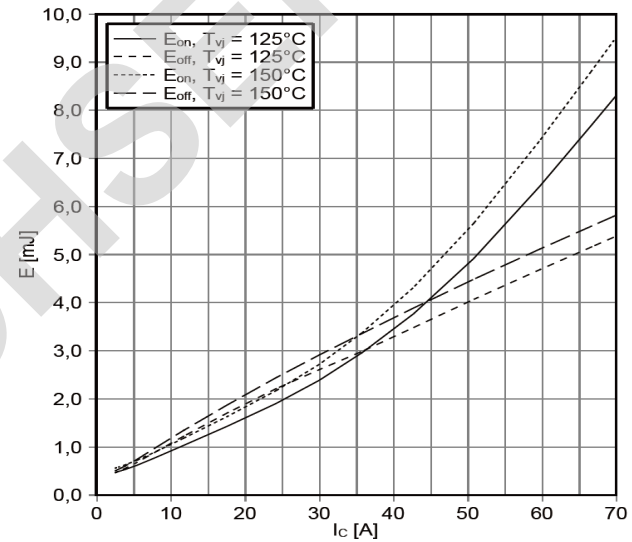
transfer characteristic IGBT, Inverter (typical)

$I_c = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



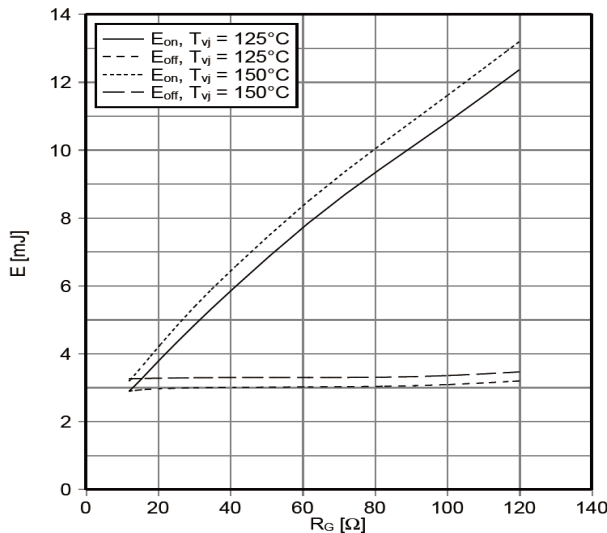
switching losses IGBT, Inverter (typical)

$E_{on} = f(I_c)$, $E_{off} = f(I_c)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 12\ \Omega$, $R_{Goff} = 12\ \Omega$, $V_{CE} = 600\text{ V}$



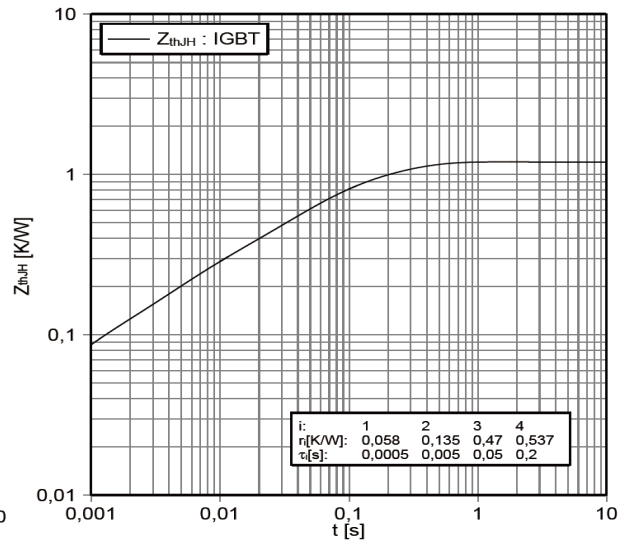
switching losses IGBT, Inverter (typical)

$E_{on} = f(R_G)$, $E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}$, $I_c = 35\text{ A}$, $V_{CE} = 600\text{ V}$



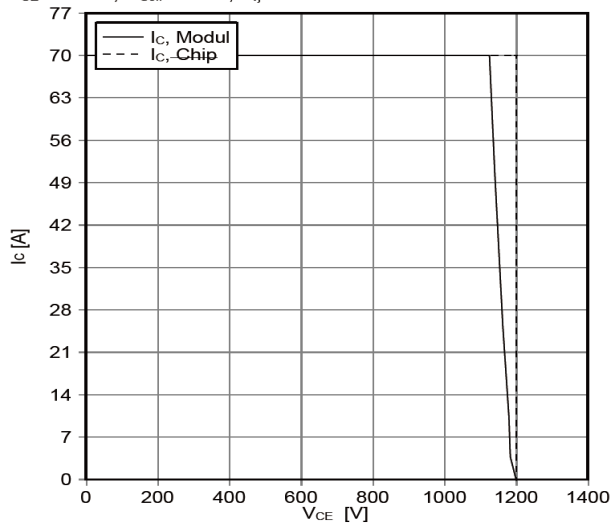
transient thermal impedance IGBT, Inverter

$Z_{thJH} = f(t)$



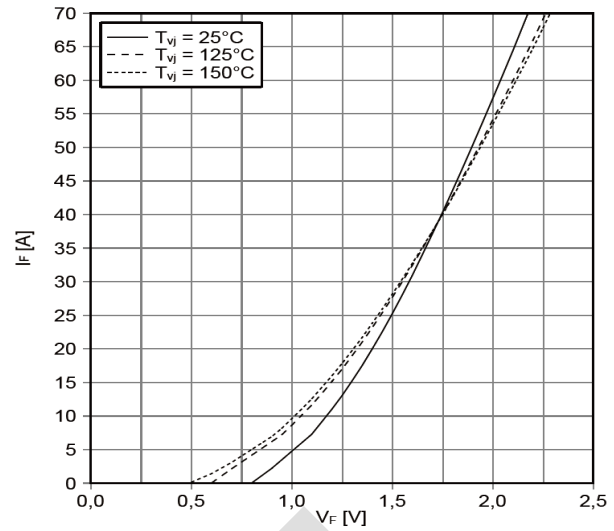
reverse bias safe operating area IGBT, Inverter (RBSOA)

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15\text{ V}$, $R_{Goff} = 12\ \Omega$, $T_{vj} = 150^\circ\text{C}$



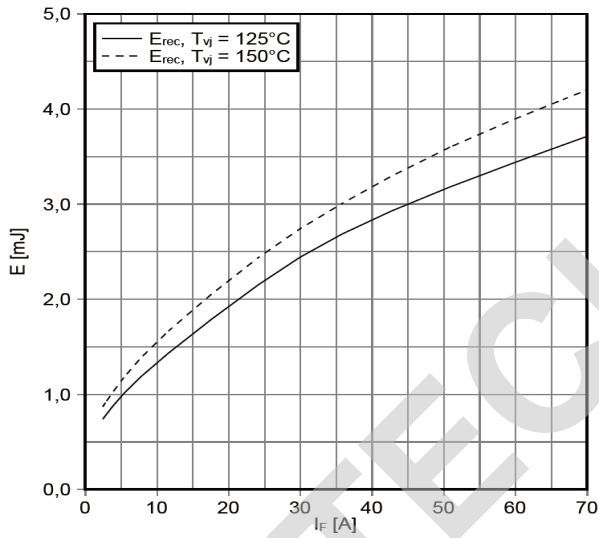
forward characteristic of Diode, Inverter (typical)

$I_F = f(V_F)$



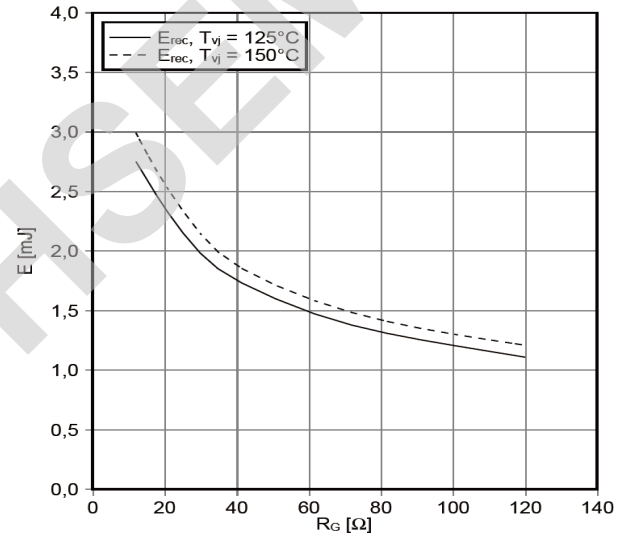
switching losses Diode, Inverter (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 12\ \Omega$, $V_{CE} = 600\text{ V}$



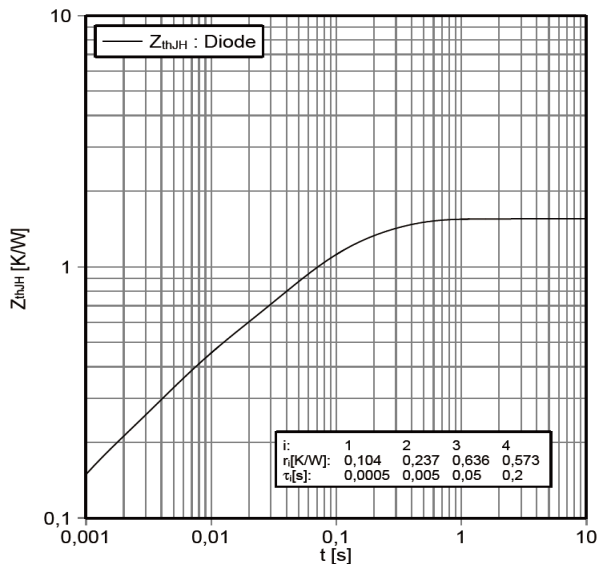
switching losses Diode, Inverter (typical)

$E_{rec} = f(R_G)$
 $I_F = 35\text{ A}$, $V_{CE} = 600\text{ V}$



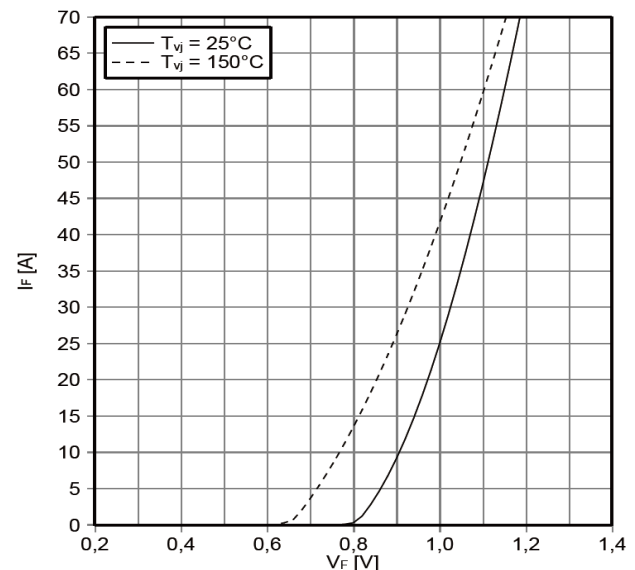
transient thermal impedance Diode, Inverter

$Z_{thJH} = f(t)$



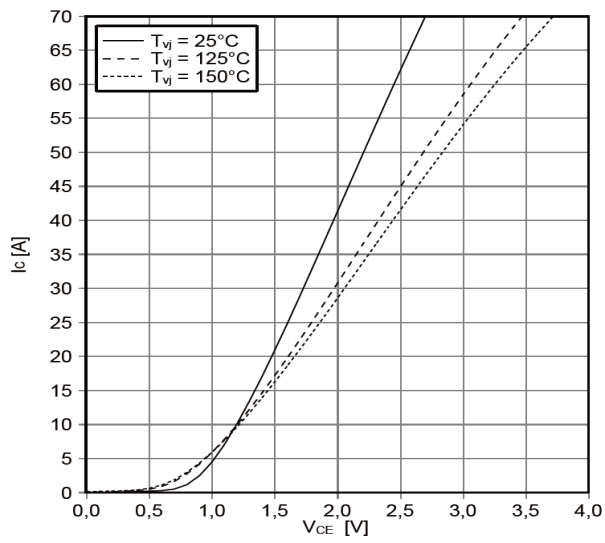
forward characteristic of Diode, Rectifier (typical)

$I_F = f(V_F)$



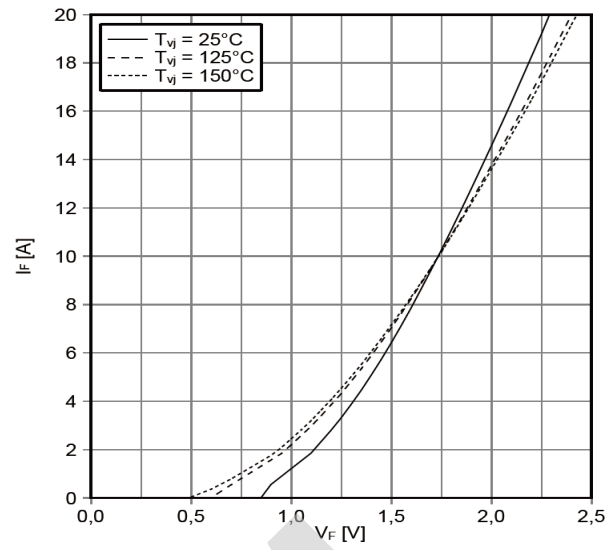
output characteristic IGBT, Brake-Chopper (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



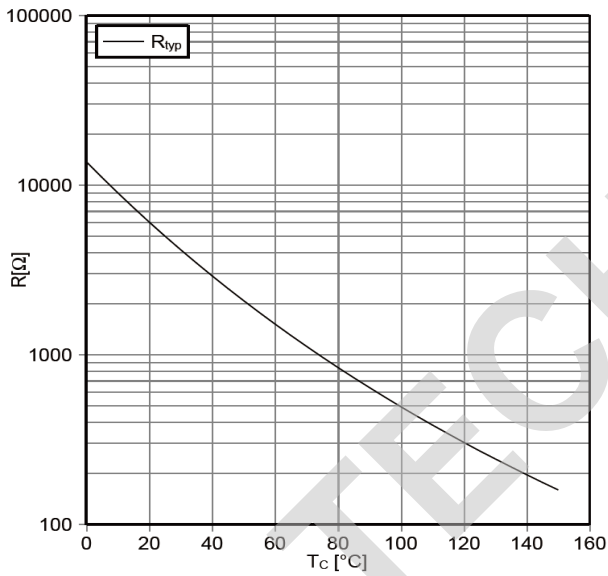
forward characteristic of Diode, Brake-Chopper (typical)

$I_F = f(V_F)$

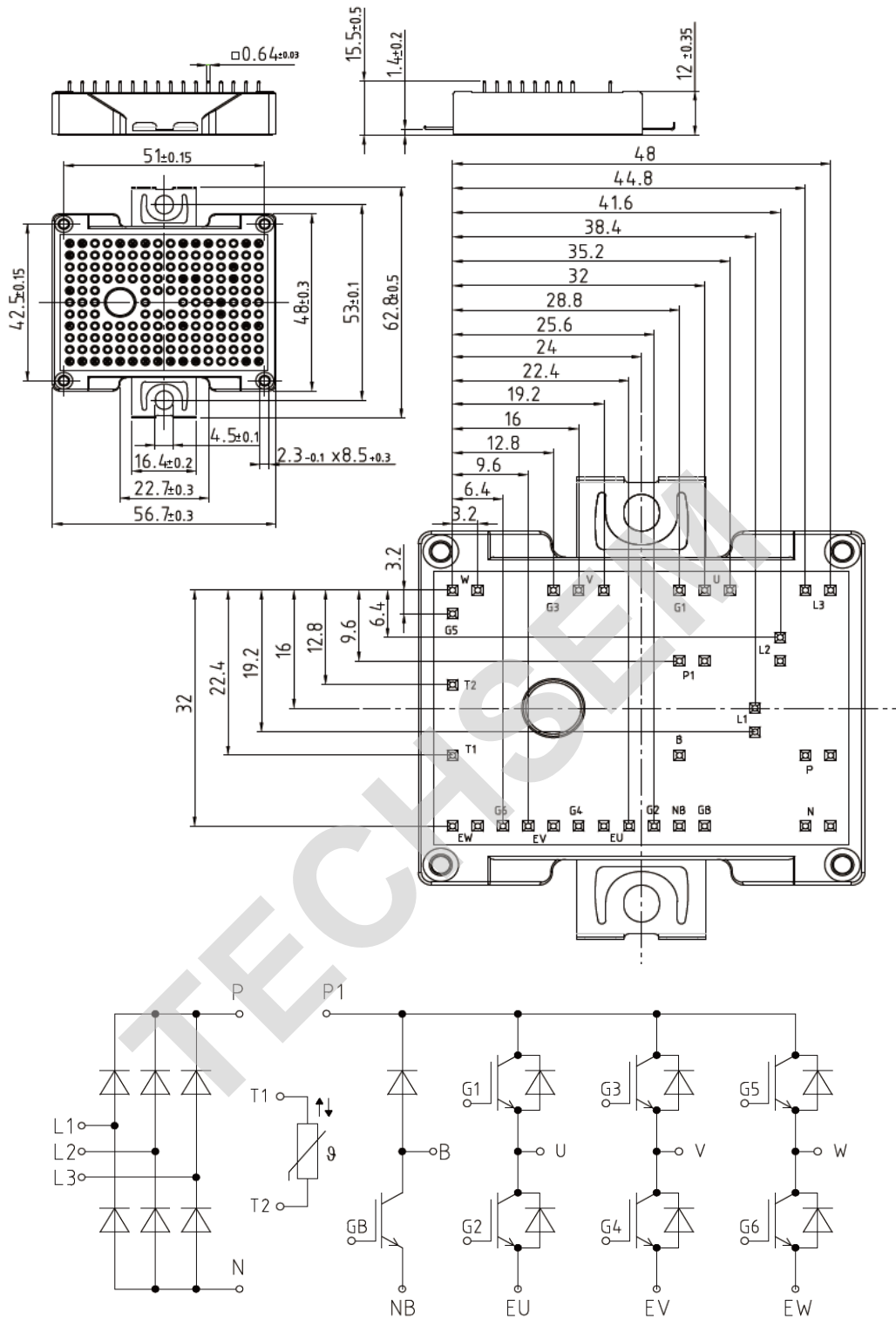


NTC-Thermistor-temperature characteristic (typical)

$R = f(T)$



Outline:



Unmarked dimensional tolerance: ±0.5mm

TECHSEM reserves the right to change specifications without notice.